

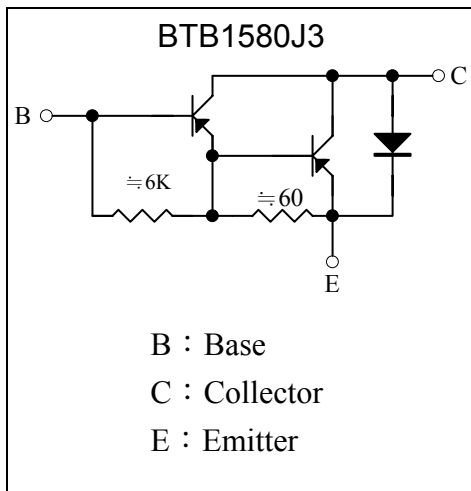
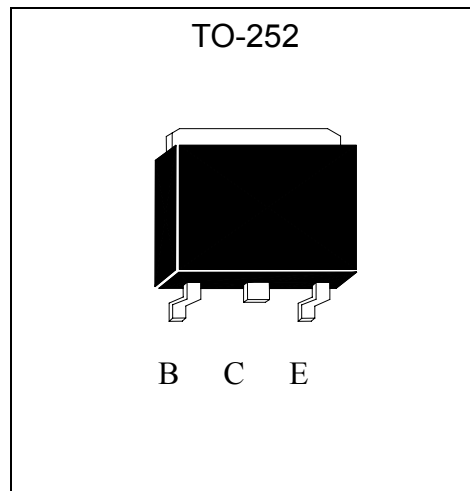
PNP Epitaxial Planar Transistor

BTB1580J3

BV_{CEO}	-120V
I_C	-4A
R_{CESAT}	600m Ω

Description

The BTB1580J3 is a PNP Darlington transistor, designed for use in general purpose amplifier and low speed switching application. Pb-free package process is adopted.

Equivalent Circuit

Outline

Absolute Maximum Ratings ($T_a=25^\circ\text{C}$)

Parameter	Symbol	Limits	Unit
Collector-Base Voltage	V_{CB0}	-120	V
Collector-Emitter Voltage	V_{CEO}	-120	V
Emitter-Base Voltage	V_{EB0}	-5	V
Collector Current (DC)	I_C	-4	A
Collector Current (Pulse)	I_{CP}	-6	A
Power Dissipation($T_A=25^\circ\text{C}$)	P_d	1.5	W
Power Dissipation($T_C=25^\circ\text{C}$)		20	W
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	83.3	$^\circ\text{C/W}$
Thermal Resistance, Junction to Case	$R_{\theta JC}$	6.25	$^\circ\text{C/W}$
Junction Temperature	T_j	150	$^\circ\text{C}$
Storage Temperature	T_{stg}	-55~+150	$^\circ\text{C}$

Note : Single Pulse $P_w \leq 300\mu\text{s}$, Duty $\leq 2\%$.

Characteristics (Ta=25°C)

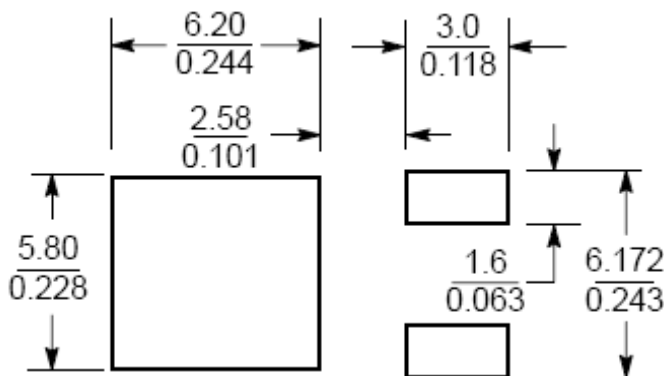
Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BV _{CEO}	-120	-	-	V	I _C =-1mA, I _B =0
BV _{CBO}	-120	-	-	V	I _C =-100μA, I _E =0
I _{CBO}	-	-	-1	mA	V _{CB} =-100V, I _E =0
I _{CEO}	-	-	-2	mA	V _{CE} =-50V, I _B =0
I _{EBO}	-	-	-2	mA	V _{EB} =-5V, I _C =0
*V _{CE(sat)}	-	-	-2	V	I _C =-2A, I _B =-2mA
*V _{BE(on)}			-2.8	V	V _{CE} =-4V, I _C =-2A
*h _{FE1}	1000	-	-	-	V _{CE} =-4V, I _C =-1A
*h _{FE2}	500	-	-	-	V _{CE} =-4V, I _C =-2A
Cob	-		200	pF	V _{CB} =-10V, I _E =0A, f=1MHz

*Pulse Test : Pulse Width ≤380μs, Duty Cycle ≤2%

Ordering Information

Device	Package	Shipping	Marking
BTB1580J3	TO-252 (Pb-free)	2500 pcs / Tape & Reel	B1580

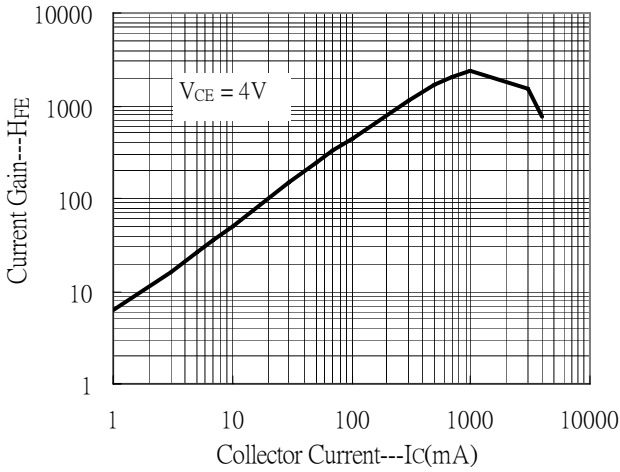
Recommended soldering footprint



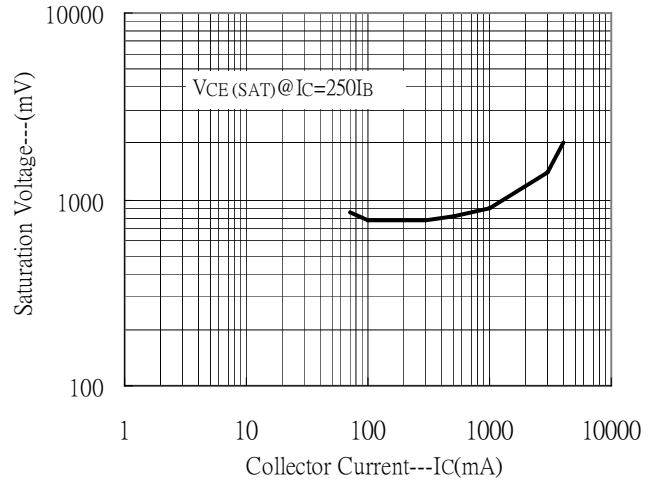
Unit ($\frac{\text{mm}}{\text{inch}}$)

Characteristic Curves

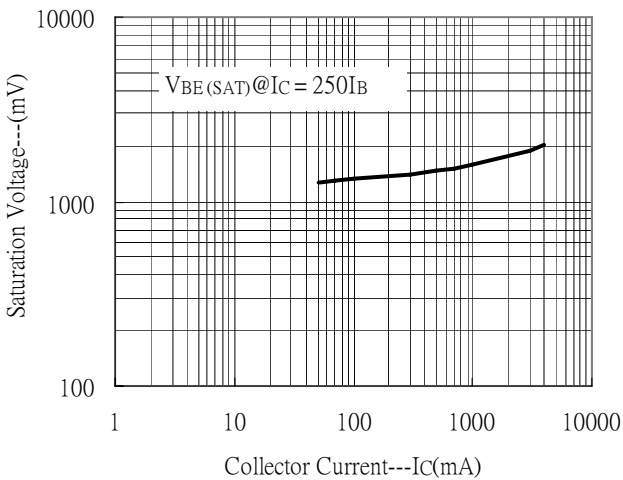
Current Gain vs Collector Current



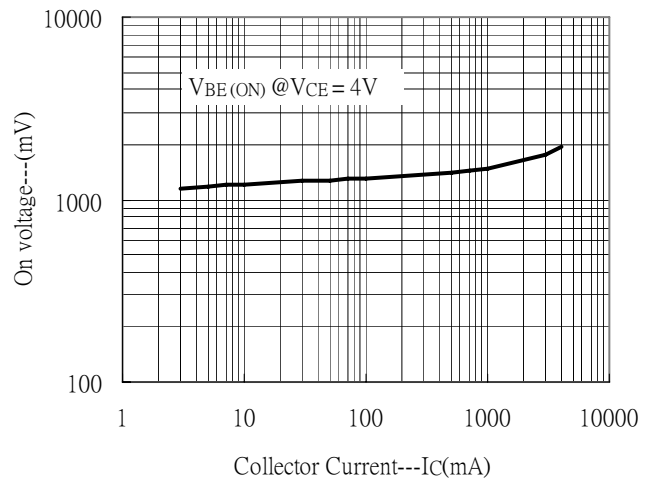
Saturation Voltage vs Collector Current



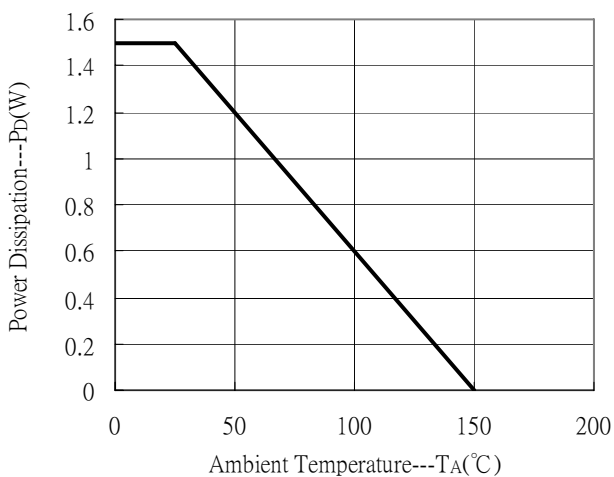
Saturation Voltage vs Collector Current



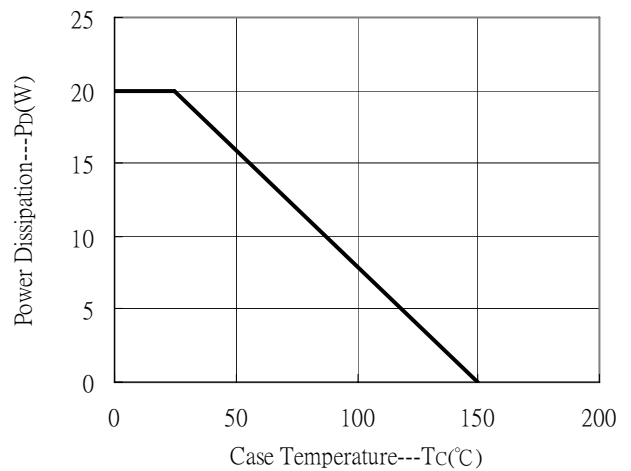
On voltage vs Collector Current



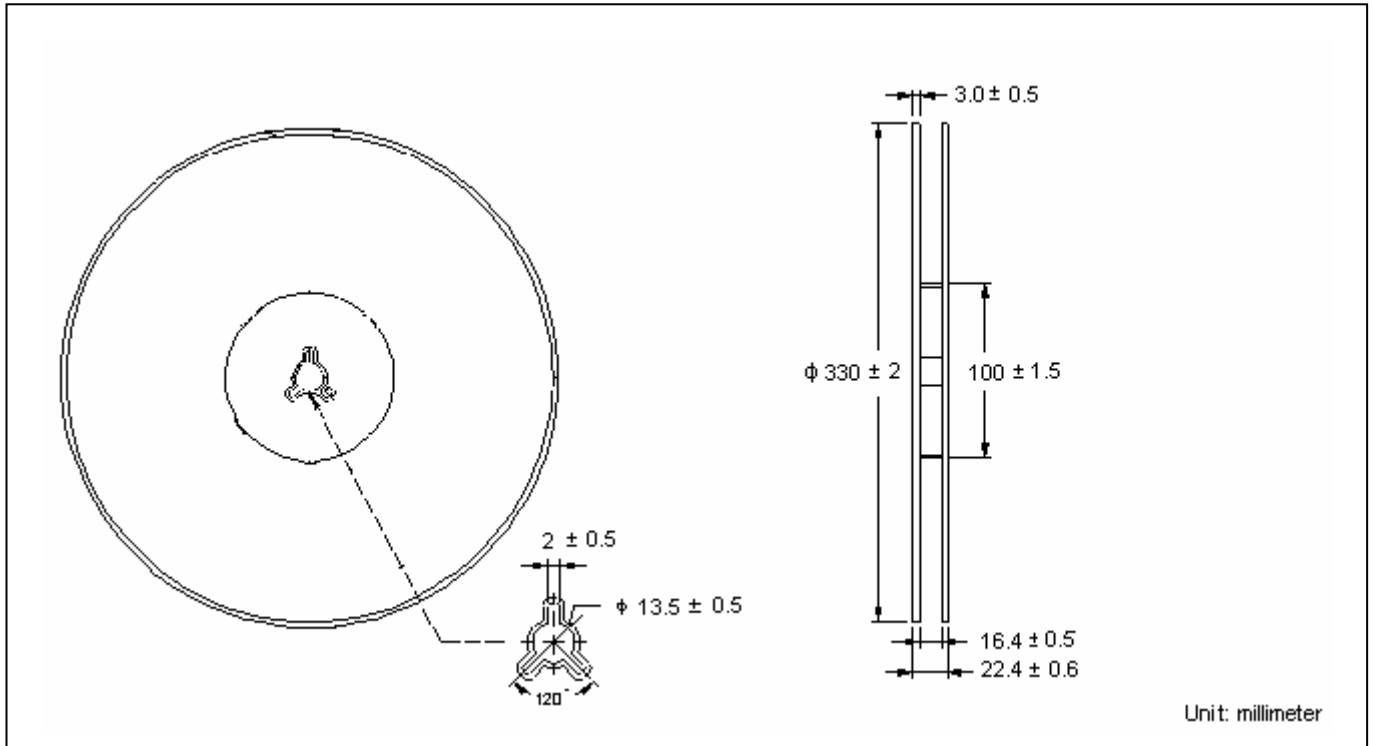
Power Derating Curve



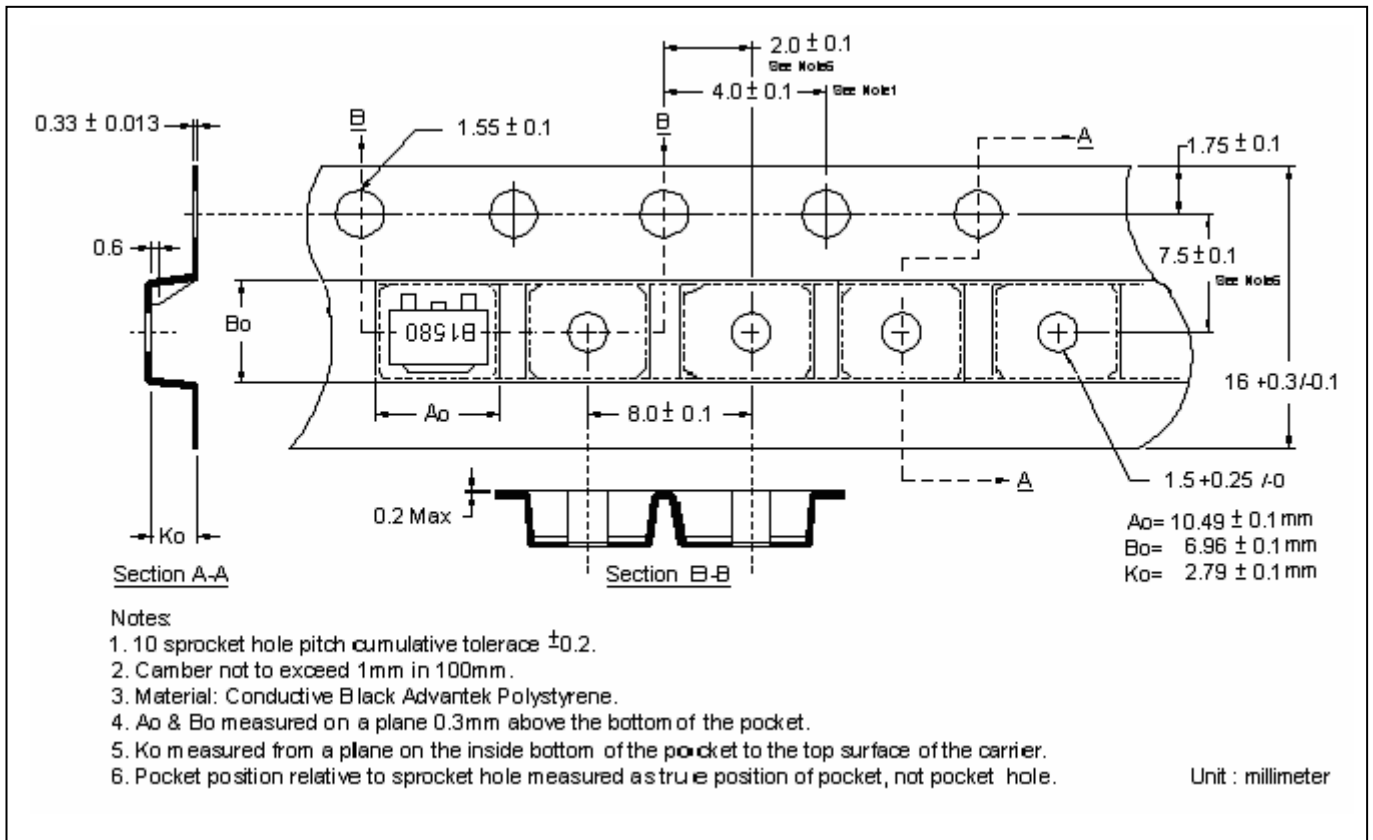
Power Derating Curve



Reel Dimension

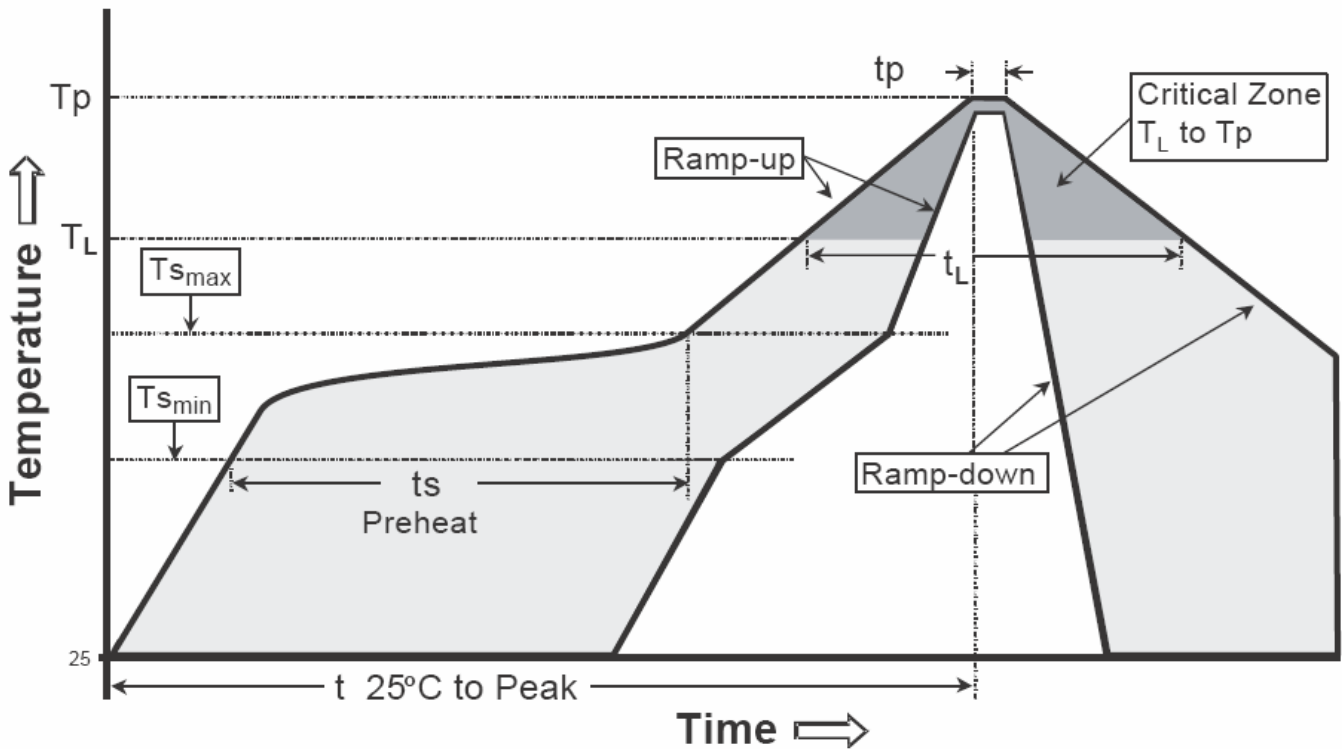


Carrier Tape Dimension



Recommended wave soldering condition

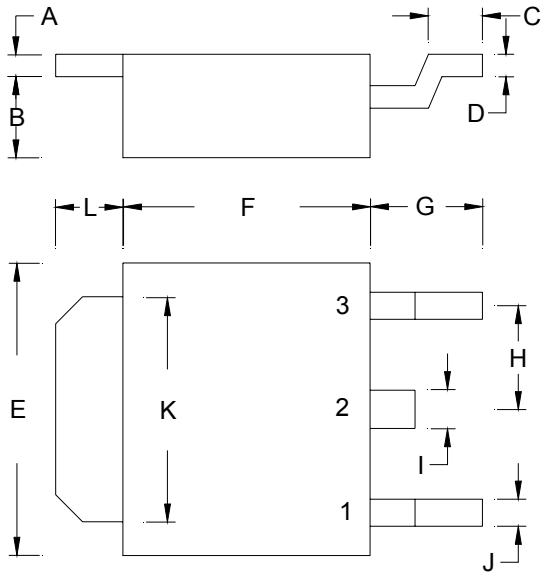
Product	Peak Temperature	Soldering Time
Pb-free devices	260 +0/-5 °C	5 +1/-1 seconds

Recommended temperature profile for IR reflow


Profile feature	Sn-Pb eutectic Assembly	Pb-free Assembly
Average ramp-up rate (Tsmax to Tp)	3°C/second max.	3°C/second max.
Preheat		
-Temperature Min(Ts min)	100°C	150°C
-Temperature Max(Ts max)	150°C	200°C
-Time(ts min to ts max)	60-120 seconds	60-180 seconds
Time maintained above:		
-Temperature (TL)	183°C	217°C
- Time (tL)	60-150 seconds	60-150 seconds
Peak Temperature(TP)	240 +0/-5 °C	260 +0/-5 °C
Time within 5°C of actual peak temperature(tp)	10-30 seconds	20-40 seconds
Ramp down rate	6°C/second max.	6°C/second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

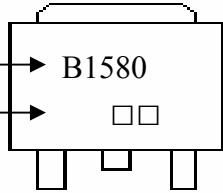
Note : All temperatures refer to topside of the package, measured on the package body surface.

TO-252 Dimension



The diagram shows two views of the TO-252 package. The top view shows dimensions A (lead height), B (body height), C (lead thickness), and D (lead width). The bottom view shows dimensions E (total height), F (body length), G (lead length), H (lead spacing), I (lead width), J (lead thickness), K (body width), L (lead offset), and pin numbers 1, 2, and 3.

Marking:



Device Name → B1580
 Date Code → □ □

Style: Pin 1.Base 2.Collector 3.Emitter

3-Lead TO-252 Plastic Surface Mount Package
 CYStek Package Code: J3

*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.0177	0.0217	0.45	0.55	G	0.0866	0.1102	2.20	2.80
B	0.0650	0.0768	1.65	1.95	H	-	*0.0906	-	*2.30
C	0.0354	0.0591	0.90	1.50	I	-	0.0449	-	1.14
D	0.0177	0.0236	0.45	0.60	J	-	0.0346	-	0.88
E	0.2441	0.2677	6.20	6.80	K	0.2047	0.2165	5.20	5.50
F	0.2125	0.2283	5.40	5.80	L	0.0551	0.0630	1.40	1.60

Notes: 1.Controlling dimension: millimeters.
 2.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 3.If there is any question with packing specification or packing method, please contact your local CYStek sales office.

Material:

- Lead: KFC; tin plating
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

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